

L Number	Hits	Search Text	DB	Time stamp
1	3160819	carrier substrate pcb board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/17 12:53
2	459543	((split hole via passage opening) with (carrier substrate pcb board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/17 12:55
3	94443	((semiconductor die chip dice ic (integrated adj circuit)) same ((split hole via passage opening) with (carrier substrate pcb board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/17 12:57
4	9182	wires same ((semiconductor die chip dice ic (integrated adj circuit)) same ((split hole via passage opening) with (carrier substrate pcb board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/17 12:58
5	3207	((wires same ((semiconductor die chip dice ic (integrated adj circuit)) same ((split hole via passage opening) with (carrier substrate pcb board)))) and (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/17 12:58
6	2072	((wires same ((semiconductor die chip dice ic (integrated adj circuit)) same ((split hole via passage opening) with (carrier substrate pcb board)))) and (bump ball)) and (resin sealing encapsulating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/17 13:01
7	1		USPAT	2003/05/17 13:39
8	1		USPAT	2003/05/17 13:39
9	1		USPAT	2003/05/17 13:39
10	1		USPAT	2003/05/17 13:39
11	1		USPAT	2003/05/17 13:39
12	1		USPAT	2003/05/17 13:39
13	1		USPAT	2003/05/17 13:39
14	1		USPAT	2003/05/17 13:40
15	1		USPAT	2003/05/17 13:40
16	1		USPAT	2003/05/17 13:40
17	1		USPAT	2003/05/17 13:40
18	1		USPAT	2003/05/17 13:40
19	1		USPAT	2003/05/17 13:41
20	1		USPAT	2003/05/17 13:41
21	1		USPAT	2003/05/17 13:41
22	1		USPAT	2003/05/17 13:41
23	1		USPAT	2003/05/17 13:41
24	1		USPAT	2003/05/17 13:41
25	1		USPAT	2003/05/17 13:41